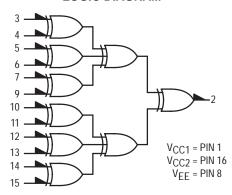
# 12-Bit Parity Generator-Checker

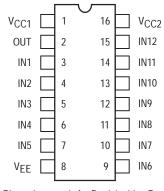
The MC10160 consists of nine Exclusive-OR gates in a single package, internally connected to provide odd parity checking or generation. Output goes high when an odd number of inputs are high. Unconnected inputs are pulled to low logic levels allowing parity detection and generation for less than 12 bits.

- $P_D = 320 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 5.0 \text{ ns typ}$
- $t_r$ ,  $t_f = 2.0$  ns typ (20%–80%)

#### **LOGIC DIAGRAM**



#### **DIP PIN ASSIGNMENT**



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

INPUT	OUTPUT
Sum of High Level Inputs	Pin 2
Even	Low
Odd	High



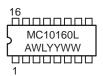
#### ON Semiconductor

http://onsemi.com

#### MARKING DIAGRAMS

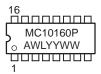


CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

#### **ORDERING INFORMATION**

Device	Package	Shipping		
MC10160L	CDIP-16	25 Units / Rail		
MC10160P	PDIP-16	25 Units / Rail		
MC10160FN	PLCC-20	46 Units / Rail		

#### **ELECTRICAL CHARACTERISTICS**

						٦	Test Limits	5			
Characteristic		Symbol	Pin Under	−30°C		+25°C		+85°C		1	
			Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain Current		ΙE	8		86		62	78		86	mAdc
Input Current		linH (Note 1.)	3 4		425 350			265 220		265 220	μAdc
		linL	3	0.5		0.5			0.3		μAdc
Output Voltage	Logic 1	Voн	2	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	Vdc
Output Voltage	Logic 0	V <sub>OL</sub>	2	-1.890	-1.675	-1.850		-1.650	-1.825	-1.615	Vdc
Threshold Voltag	e Logic 1	Vона	2	-1.080		-0.980			-0.910		Vdc
Threshold Voltag	e Logic 0	VOLA	2		-1.655			-1.630		-1.595	Vdc
Switching Times (50Ω Load)											ns
Propagation Dela	vy	t3+2+ t3+2- t3-2- t3-2+ t4+2+ t4+2- t4-2- t4-2+	2 2 2 2 2 2 2 2 2	1.8 1.8 1.8 1.8 1.8 1.8 1.8	8.1 8.1 8.1 8.1 8.1 8.1 8.1	2.0 2.0 2.0 2.0 2.0 2.0 2.0 2.0	5.0 5.0 5.0 5.0 5.0 5.0 5.0 5.0	7.5 7.5 7.5 7.5 7.5 7.5 7.5 7.5	2.0 2.0 2.0 2.0 2.0 2.0 2.0 2.0	8.0 8.0 8.0 8.0 8.0 8.0 8.0	
Rise Time	(20 to 80%)	t <sub>2+</sub>	2	1.1	3.5	1.1	2.0	3.3	1.0	3.5	
Fall Time	(20 to 80%)	t <sub>2</sub> _	2	1.1	3.5	1.1	2.0	3.3	1.0	3.5	

<sup>1.</sup> Pins 3, 6, 7, 11, 12, 15 are similar. Pins 4, 5, 9, 10, 13, 14 are similar.

#### **ELECTRICAL CHARACTERISTICS** (continued)

					TEST VOLTA	GE VALUES	(Volts)		
@ Test Temperature			V <sub>IHmax</sub>	V <sub>ILmin</sub>	VIHAmin	V <sub>ILAmax</sub>	VEE		
–30°C				-0.890	-1.890	-1.205	-1.500	-5.2	
		+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	1	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	1
Pin			TEST	TEST VOLTAGE APPLIED TO PINS LISTED BELOW					
Characteristic	:	Symbol	Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	VIHAmin	V <sub>ILAmax</sub>	VEE	(VCC)
Power Supply Drain Co	urrent	ΙΕ	8	4,5,9, 10,13,14				8	1,16
Input Current		linH (Note 1.)	3 4	3 4				8 8	1,16 1,16
		l <sub>inL</sub>	3		3			8	1,16
Output Voltage	Logic 1	Vон	2	3	4,5,6,7,9,10, 11,12,13,14,15			8	1,16
Output Voltage	Logic 0	V <sub>OL</sub>	2		3,4,5,6,7,9,10, 11,12,13,14,15			8	1,16
Threshold Voltage	Logic 1	Vона	2		4,5,6,7,9,10, 11,12,13,14,15	3		8	1,16
Threshold Voltage	Logic 0	V <sub>OLA</sub>	2		3,5,6,7,9,10, 11,12,13,14,15		4	8	1,16
Switching Times (50	Ω Load)			+1.11V		Pulse In	Pulse Out	−3.2 V	+2.0 V
Propagation Delay		t3+2+ t3+2- t3-2- t3-2+ t4+2+ t4+2- t4-2- t4-2+	2 2 2 2 2 2 2 2	4 4 3 3		3 3 3 3 4 4 4 4	2 2 2 2 2 2 2 2	8 8 8 8 8 8	1,16 1,16 1,16 1,16 1,16 1,16 1,16 1,16
Rise Time (20	to 80%)	t <sub>2+</sub>	2			3	2	8	1,16
Fall Time (20	to 80%)	t <sub>2</sub> _	2			3	2	8	1,16

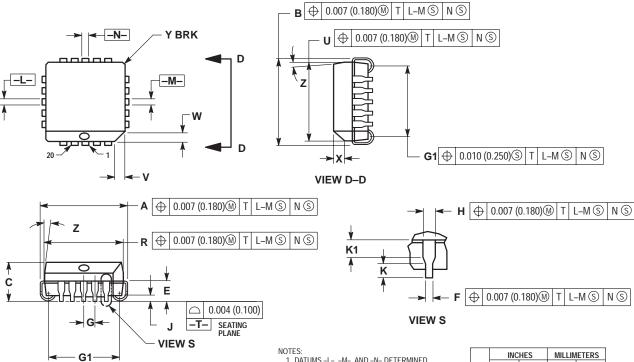
<sup>1.</sup> Pins 3, 6, 7, 11, 12, 15 are similar. Pins 4, 5, 9, 10, 13, 14 are similar.

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

#### PACKAGE DIMENSIONS

#### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



#### NOTES:

⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- DATUMS -L-, -M-, AND -N- DETERMINED
   WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
  4. DIMENSIONING AND TOLERANCING PER ANSI

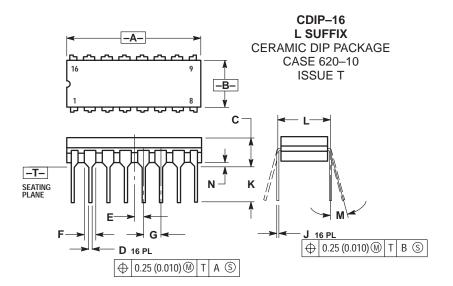
- 714.5M, 1982.

  5. CONTROLLING DIMENSION: INCH.

  6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO .012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

INC	HES	MILLIMETERS		
MIN	MAX	MIN	MAX	
0.385	0.395	9.78	10.03	
0.385	0.395	9.78	10.03	
0.165	0.180	4.20	4.57	
0.090	0.110	2.29	2.79	
0.013	0.019	0.33	0.48	
0.050	BSC	1.27	BSC	
0.026	0.032	0.66	0.81	
0.020		0.51		
0.025		0.64		
0.350	0.356	8.89	9.04	
0.350	0.356	8.89	9.04	
0.042	0.048	1.07	1.21	
0.042	0.048	1.07	1.21	
0.042	0.056	1.07	1.42	
	0.020		0.50	
2°	10 °	2 °	10 °	
0.310	0.330	7.88	8.38	
0.040		1.02		
	MIN 0.385 0.385 0.165 0.090 0.013 0.050 0.026 0.020 0.350 0.350 0.042 0.042 0.042 0.042 0.0310 0.0310	0.385 0.395 0.385 0.395 0.165 0.180 0.090 0.110 0.013 0.019 0.050 BSC 0.026 0.032 0.020 0.350 0.356 0.350 0.356 0.042 0.048 0.042 0.048 0.042 0.056 0.020 0.20 10° 0.310 0.330	MIN         MAX         MIN           0.385         0.395         9.78           0.385         0.395         9.78           0.385         0.395         9.78           0.385         0.395         9.78           0.160         0.180         4.20           0.090         0.110         2.29           0.013         0.019         0.33           0.056         D.2         1.27           0.026         0.032         0.66           0.020          0.51           0.025          0.64           0.350         0.356         8.89           0.350         0.356         8.89           0.042         0.048         1.07           0.042         0.048         1.07            0.020             0.020         1.07            0.025         1.07            0.020            0.042         0.048         1.07            0.020            0.042         0.045         1.07            0.020	

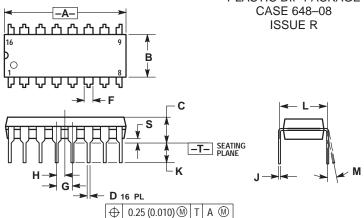
#### **PACKAGE DIMENSIONS**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.015 0.020		0.50	
Ε	0.050	) BSC	1.27 BSC		
F	0.055	0.055 0.065		1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62	BSC	
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

#### PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

# **Notes**

# **Notes**

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